



SOT1183-1

plastic thermal enhanced extremely thin quad flat package;
no leads; 16 terminals

5 March 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HXQFN16
Package type industry code	HXQFN16
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	29-07-2010
Manufacturer package code	SOT1183

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.9	3	3.1	mm
seated height	-	-	0.5	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	16	-	

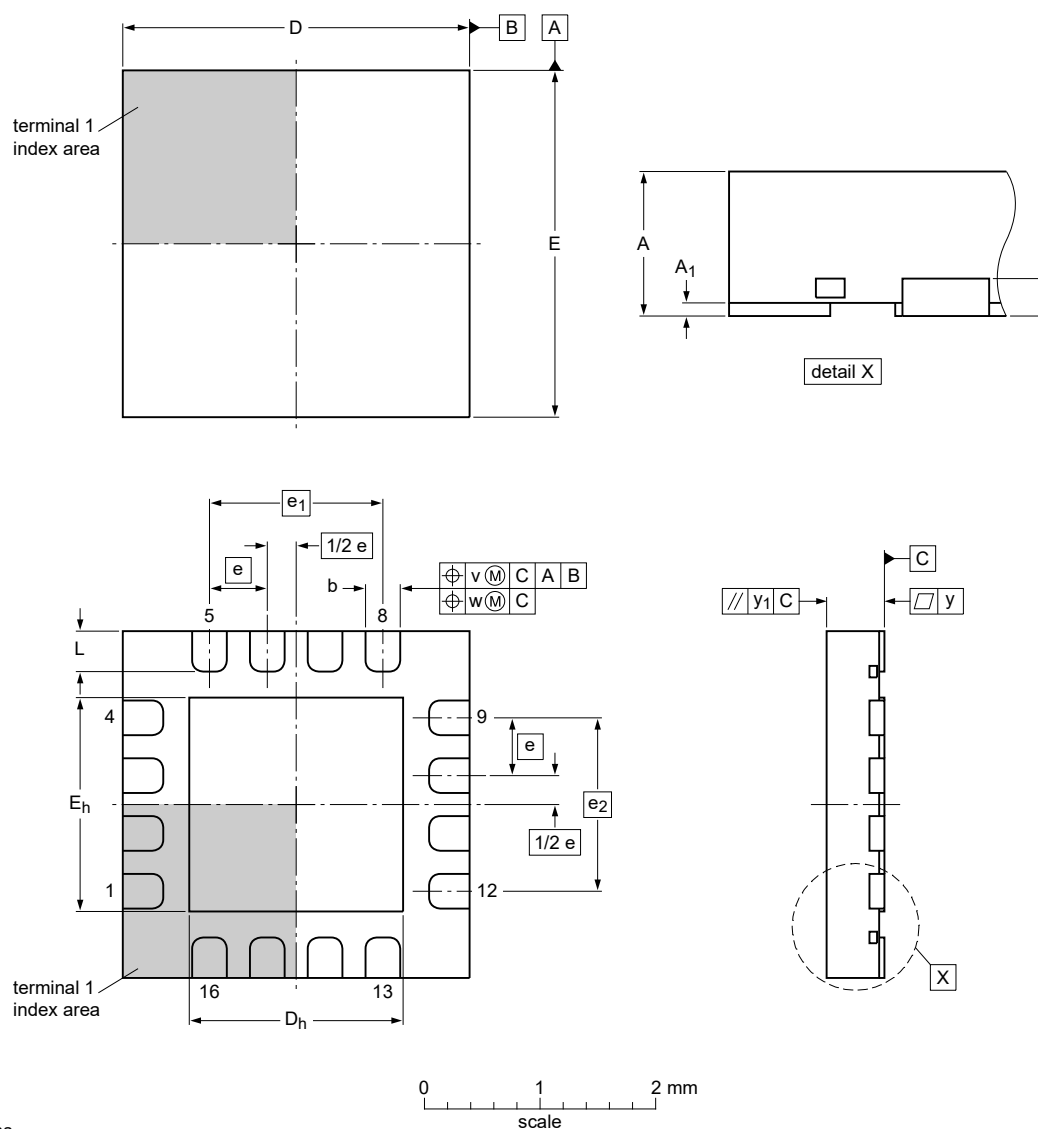


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2 Package outline

HXQFN16: plastic thermal enhanced extremely thin quad flat package; no leads; 16 terminals; body 3 x 3 x 0.5 mm

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Dimensions										scale							
Unit		A	A ₁	b	c	D	D _h	E	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
mm	max	0.5	0.05	0.35		3.1	1.95	3.1	1.95				0.40				
	nom			0.30	0.127	3.0	1.85	3.0	1.85				0.35	0.1	0.05	0.05	0.1
	min		0.00	0.25		2.9	1.75	2.9	1.75	0.5	1.5	1.5	0.30				

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Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1183-1	---		---			10-07-15 10-07-29

Figure 1. Package outline HXQFN16 (SOT1183-1)

3 Legal information

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